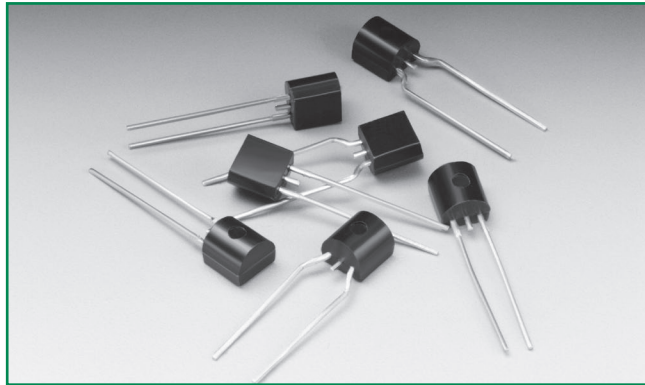


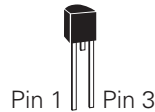
MC Series - TO-92



Agency Approvals

Agency	Agency File Number
	E133083

Pinout Designation



Schematic Symbol



Description

MC Series TO-92 are low capacitance SIDACtor® devices designed to protect broadband CPE equipment such as VoIP and DSL Modems from damaging overvoltage transients.

The series provides a through-hole solution that enables CPE equipment to comply with global regulatory standards while limiting the impact to broadband signals.

Features and Benefits

- Low voltage overshoot
- Low on-state voltage
- Does not degrade surge capability after multiple surge events within limit
- Fails short circuit when surged in excess of ratings
- 40% lower capacitance than our Baseband Protectors, for applications that demand greater signal integrity
- 2nd level interconnect is Pb-free per IPC/ JEDEC J-STD-609A.01

Applicable Global Standards

- TIA-968-A
- TIA-968-B
- ITU K.20/21 Enhanced Level
- ITU K.20/21 Basic Level
- GR 1089 Intra-building
- IEC 61000-4-5
- YD/T 1082
- YD/T 993
- YD/T 950

Electrical Characteristics

Part Number	Marking	V_{DRM} @ $I_{DRM}=5\mu A$	V_S @ $100V/\mu s$	I_H	I_S	I_T	V_T @ $I_T=2.2$ Amps	Capacitance @ 1MHz, 2V bias	
		V min	V max	mA min	mA max	A max	V max	pF min	pF max
P0080ECMCLxxx	P0080ECMC	6	25	50	800	2.2	4	35	75
P0300ECMCLxxx	P0300ECMC	25	40	50	800	2.2	4	25	45
P0640ECMCLxxx	P0640ECMC	58	77	150	800	2.2	4	55	85
P0720ECMCLxxx	P0720ECMC	65	88	150	800	2.2	4	50	75
P0900ECMCLxxx	P0900ECMC	75	98	150	800	2.2	4	45	70
P1100ECMCLxxx	P1100ECMC	90	130	150	800	2.2	4	45	70
P1300ECMCLxxx	P1300ECMC	120	160	150	800	2.2	4	40	60
P1500ECMCLxxx	P1500ECMC	140	180	150	800	2.2	4	35	55
P1800ECMCLxxx	P1800ECMC	170	220	150	800	2.2	4	35	50
P2300ECMCLxxx	P2300ECMC	190	260	150	800	2.2	4	30	50
P2600ECMCLxxx	P2600ECMC	220	300	150	800	2.2	4	30	45
P3100ECMCLxxx	P3100ECMC	275	350	150	800	2.2	4	30	45
P3500ECMCLxxx	P3500ECMC	320	400	150	800	2.2	4	25	40

Notes:

- Absolute maximum ratings measured at $T_a = 25^\circ C$ (unless otherwise noted).
- Devices are bi-directional (unless otherwise noted).
- **XXX** Part Number Suffix: **'AP'** (Ammo Pack), or **'RP1'** or **'RP2'** (Reel Pack),.

Surge Ratings

Series	I _{PP}									I _{TSM} 50/60 Hz	di/dt
	0.2x310 ¹ 0.5x700 ²	2x10 ¹ 2x10 ²	8x20 ¹ 1.2x50 ²	10x160 ¹ 10x160 ²	10x560 ¹ 10x560 ²	5x320 ¹ 9x720 ²	10x360 ¹ 10x360 ²	10x1000 ¹ 10x1000 ²	5x310 ¹ 10x700 ²		
	A min	A min	A min	A min	A min	A min	A min	A min	A min		
C	50	500	400	200	150	200	175	100	200	30	500

Notes:

1 Current waveform in μs

2 Voltage waveform in μs

- Peak pulse current rating (I_{PP}) is repetitive and guaranteed for the life of the product.

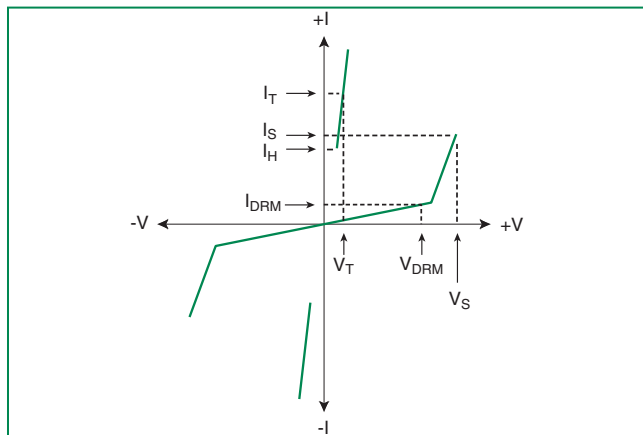
- I_{PP} ratings applicable over temperature range of -40°C to +85°C

- The device must initially be in thermal equilibrium with -40°C ≤ T_J ≤ +150°C

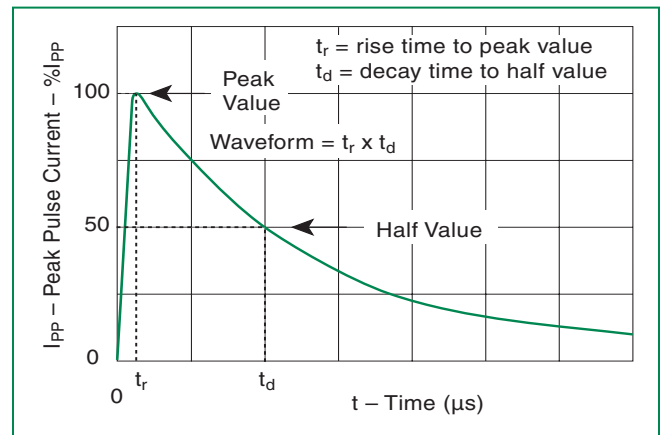
Thermal Considerations

Package	Symbol	Parameter	Value	Unit
 TO-92	T_J	Operating Junction Temperature Range	-40 to +150	°C
	T_S	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	90	°C/W

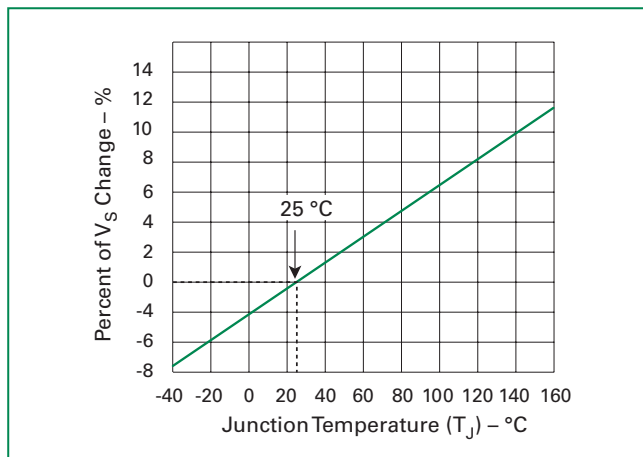
V-I Characteristics



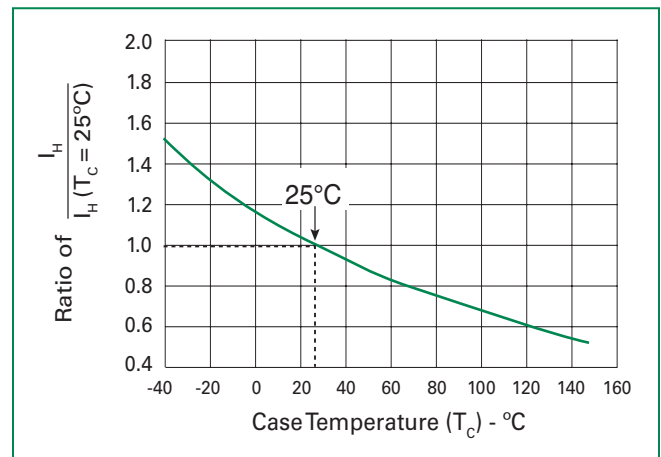
$t_r \times t_d$ Pulse Waveform



Normalized V_S Change vs. Junction Temperature

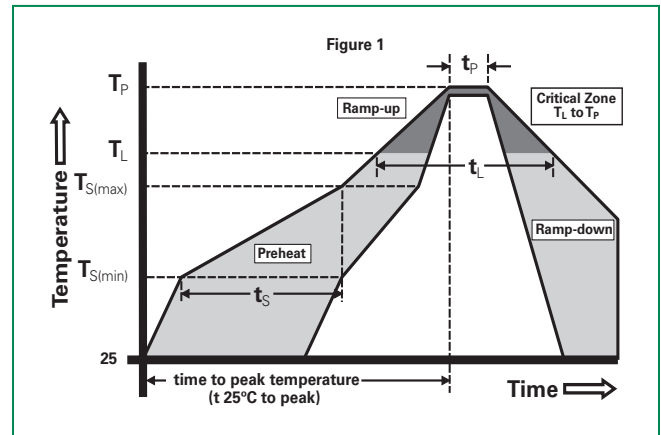


Normalized DC Holding Current vs. Case Temperature



Soldering Parameters

Reflow Condition		Pb-Free assembly (see Fig. 1)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max ($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max.
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max.
Reflow	-Temperature (T_L) (Liquidus)	+217°C
	-Temperature (t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to Peak Temp (T_p)		8 min. Max.
Do not exceed		+260°C



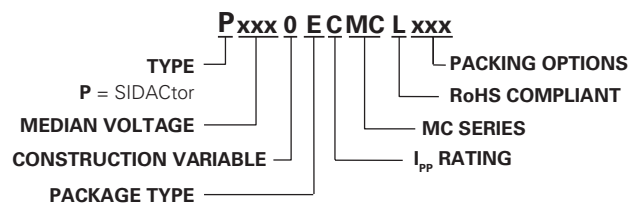
Physical Specifications

Lead Material	Copper Alloy
Terminal Finish	100% Matte-Tin Plated
Body Material	UL recognized epoxy meeting flammability classification 94V-0

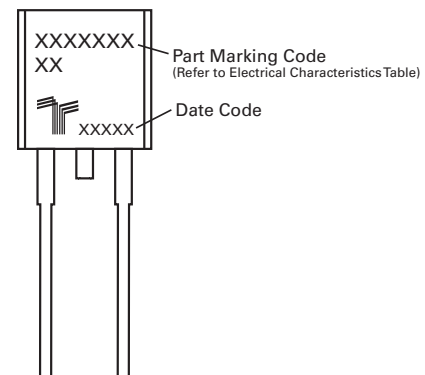
Environmental Specifications

High Temp Voltage Blocking	80% Rated V_{DRM} ($V_{AC Peak}$) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
Temp Cycling	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A-104
Biased Temp & Humidity	52 V_{DC} (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
High Temp Storage	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
Low Temp Storage	-65°C, 1008 hrs.
Thermal Shock	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
Autoclave (Pressure Cooker Test)	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
Resistance to Solder Heat	+260°C, 30 secs. MIL-STD-750 (Method 2031)
Moisture Sensitivity Level	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

Part Numbering



Part Marking



Package Type	Description	Packing Options Quantity	Added Suffix	Lead Spacing	Industry Standard
E	TO-92 Tape and Reel Pack	2000	RP1	0.1 inch (2.54mm)	EIA-481-D
			RP2	0.2 inch (5.08mm)	
	TO-92 Ammo Pack		AP	(Not applicable)	EIA-468-B
	TO-92 Bulk Pack		N/A	(Not applicable)	N/A

	Inches		Millimeters	
	Min	Max	Min	Max
A	0.176	0.196	4.47	4.98
B	0.500		12.70	
D	0.095	0.105	2.41	2.67
E	0.150		3.81	
G	0.135	0.145	3.43	3.68
H	0.088	0.096	2.23	2.44
J	0.176	0.186	4.47	4.73
K	0.088	0.096	2.23	2.44
L	0.013	0.019	0.33	0.48
M	0.013	0.017	0.33	0.43
N		0.60		1.52

Mold flash shall not exceed 0.13 mm per side.

Dimensions are in inches (and millimeters).

Direction of Feed

Flat down

25 Devices per fold

1.62 (41.2) MAX

0.236 (6.0)

0.02 (0.5)

0.708 (18.0)

0.354 (9.0)

0.50 (12.7)

0.25 (6.35)

0.125 (3.2) MAX

1.27 (32.2)

0.157 (4.0) DIA

0.50 (12.7)

0.20 (5.08)

1.7 (43)

6.9 (175)

1.7 (43)

12.9 (327)

Figure 1 illustrates the dimensions of the TO-92 package. The top view shows a circular package with diameter A, a central circular feature with diameter D, and concentric circles with diameters C and B. The side view of the flat side shows a package with width W1. The side view of the round side shows three packages with dimensions P (pitch), P0 (lead spacing), F (lead length), and H (height). The height H is divided into H1 (total height) and W (height to the base). The base width is W2. The lead width is W3. The lead length is W4. The packages are labeled (RP1) and (RP2).

	Inches		Millimeters	
	Min	Max	Min	Max
A	N/A	14.173	N/A	360.0
B	4.016	N/A	102.0	N/A
C	3.386	N/A	86.0	N/A
D	0.795	N/A	20.2	N/A
W1	1.181	1.968	30.0	50.0
P	0.496	0.504	12.60	12.80
P0	0.498	0.502	12.65	12.75
F(for RP1)	0.090	0.110	2.29	2.80
F(for RP2)	0.182	0.244	4.63	6.19
H	N/A	1.673	N/A	42.50
H1	N/A	1.270	N/A	32.26
W	0.674	0.763	17.12	19.38
W2	0.354	0.370	8.25	9.75
W3	0.236	N/A	6.00	N/A
W4	0.020	N/A	0.50	N/A